

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	1	"20040100772".PN.	US-PGPUB	OR	ON	2005/09/16 08:18
L3	1	"20030230801".PN.	US-PGPUB	OR	ON	2005/09/16 08:19
L4	1	"6777819".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:19
L5	1	"6762488".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:19
L6	1	"6746894".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:19
L7	1	"6737750".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:20
L8	1	"6734552".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:20
L9	1	"6734539".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:20
L10	1	"6716676".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:20
L11	1	"6667556".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:21
L12	1	"6649448".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:21
L13	1	"6607937".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:21
L14	1	"6593648".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:21
L15	1	"6590281".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:22
L16	1	"6552423".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:22
L17	1	"6383845".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:23
L18	1	"6545366".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:23
L19	1	"6512303".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:24
L20	1	"6472741".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:24
L21	1	"6462421".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:24
L22	1	"6414381".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:25
L23	1	"6413798".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:25
L24	1	"6407456".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:26
L25	1	"6265766".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:26
L26	1	"6157080".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:26

L27	1	"5994166".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:27
L28	1	"6157080".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:27
L29	1	"5994166".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:27
L30	1	"5744863".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:27
L31	1	"5444296".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:28
L32	1	"5222014".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:28
L34	121	@ad<="20040102" and 'MCP' and 'CSP'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 08:43
L35	0	@ad<="20040102" and 'stacked chip' and 'firs package substrate' and 'second package substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 08:45
L36	9	@ad<="20040102" and 'stacked chip' and 'first package substrate' and 'second package substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 08:45
L37	100	@ad<="20040102" and 'stacked chip' and 'package substrates'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 08:45
L39	1	"6376769".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:47
L40	1	"6218731".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:48
L41	1	"5793870".PN.	USPAT; USOCR	OR	ON	2005/09/16 08:48
S1	2	"20040201087"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:15
S2	1	'samsung' and 'dong-ho lee'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 14:52
S3	85	lee-dong-ho.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:16

S4	16	lee-dong-ho.in. and 'package'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:21
S5	2145	@ad<="20040102" and (257/678). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 14:55
S6	526	@ad<="20040102" and (257/685). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:24
S7	1654	@ad<="20040102" and (257/686). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:22
S8	835	@ad<="20040102" and (257/730). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:24
S9	3376	@ad<="20040102" and (257/777-778).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:25
S10	957	@ad<="20040102" and (257/779). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:36
S11	1307	@ad<="20040102" and (257/693). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:27
S13	33	@ad<="20040102" and 'stack package' and 'chip scale package' and 'ball grid array'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:49
S14	2040	@ad<="20040102" and (257/723). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:29
S15	1	"6376769".PN.	USPAT; USOCR	OR	ON	2005/04/21 10:29
S16	1	"6108210".PN.	USPAT; USOCR	OR	ON	2005/04/21 10:30
S17	1	"5950304".PN.	USPAT; USOCR	OR	ON	2005/04/21 10:30

S18	1	"6218731".PN.	USPAT; USOCR	OR	ON	2005/04/21 10:31
S19	1	"5793870".PN.	USPAT; USOCR	OR	ON	2005/04/21 10:32
S20	1	"5714405".PN.	USPAT; USOCR	OR	ON	2005/04/21 10:32
S22	45	@ad<="20040102" and 'chip stack' and 'chip scale package' and 'ball grid array'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:20
S23	50	@ad<="20040102" and 'chip stack' and 'CSP' and 'BGA'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:34
S24	0	@ad<="20040102" and 'chip stack' and 'chip scale package' and 'connecting board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:20
S25	3	@ad<="20040102" and 'chip stack' and 'connecting board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:20
S26	11	@ad<="20040102" and 'chip scale package' and 'connecting board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:34
S27	10	@ad<="20040102" and 'chip scale package' and 'coupled' and 'flexible circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:42
S28	14	@ad<="20040102" and 'CSP' and 'coupled' and 'flexible circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:35
S29	672	@ad<="20040102" and (257/727). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:36
S30	643	@ad<="20040102" and 'chip scale package' and 'stack'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:42
S31	46	@ad<="20040102" and 'chip scale package' and 'connect' same 'flexible' with 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:55

S32	1	"6376769".PN.	USPAT; USOCR	OR	ON	2005/04/21 13:45
S33	1	"6218731".PN.	USPAT; USOCR	OR	ON	2005/04/21 13:46
S34	1	"5793870".PN.	USPAT; USOCR	OR	ON	2005/04/21 13:46
S35	5	Cha-Ki-Bon.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:55
S36	2	"20040245628"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 14:34
S37	6	'ye-chung'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 14:52
S42	1	@ad<="20040105" and 'tape package' and 'base substrate' with 'through hole' and 'chip' and 'encapsulant' and 'copper' same 'test pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 14:58
S43	1	@ad<="20040105" and 'tape package' and 'base substrate' with 'through hole' and 'chip' and 'copper' same 'test pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 14:58
S44	2	@ad<="20040105" and 'tape package' and 'base substrate' with 'hole' and 'chip' and 'copper' same 'test pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 14:59
S45	2	@ad<="20040105" and 'tape package' and 'base substrate' with 'hole' and 'chip' and 'copper'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 14:59
S46	33	@ad<="20040105" and 'tape package' and 'substrate' with 'hole' and 'chip' and 'copper'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 15:05
S47	1	@ad<="20040105" and 'flexible' with 'tape package' and 'through hole' and 'copper' and 'test'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 15:06
S48	2	@ad<="20040105" and 'flexible' with 'tape package' and 'through hole' and 'copper'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 15:07

S49	2	@ad<="20040105" and 'flexible' with 'tape package' and 'through hole'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 15:08
S50	15	@ad<="20040105" and 'flexible' with 'tape package'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 15:10
S51	410	@ad<="20040105" and 'LCD' with 'tape' with 'package'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 15:53
S52	76	@ad<="20040105" and 'flexible' with 'tape' with 'package' and 'through-hole'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 15:52
S53	5	@ad<="20040105" and 'flexible' with 'tape' with 'package' and 'through-hole' and 'test pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 15:11
S54	204	@ad<="20040105" and 'tape' with 'package' and 'through-hole' and 'test'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 15:14
S55	34	@ad<="20040105" and 'tape' with 'package' and 'through-hole' and 'test pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 15:14
S56	2	@ad<="20040105" and 'LCD' with 'package' and 'bending slit'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 15:36
S57	2	"20020162626"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 15:40
S58	21	'mori yoichi' and 'nec'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 15:47
S59	456	@ad<="20040105" and 'flexible' with 'tape' with 'package' and 'through' with 'hole'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 15:53

S60	72	@ad<="20040105" and 'LCD' with 'tape' with 'package' and 'through' with 'hole'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 15:58
S61	3	@ad<="20040105" and 'LCD' and 'tape' with 'package' and 'through hole' and 'test pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 15:58
S62	2	@ad<="20040102" and 'chip stack' and 'CSP' and 'MCP'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:34
S63	53	@ad<="20040102" and 'chip stack' and 'CSP' and 'BGA'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:35
S64	46	@ad<="20040102" and 'MCP' and 'CSP' and 'BGA'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 08:41